

General PC Alloy WONDERLOY® PC-345

Product Description: High flow

Properties	ISO Test Method	Test Condition	Unit	PC-345
Melt Flow Index	1133	260°C×5KG	ml/10 min	19
Spiral flow	CHIMEI	260°C,2mm, V:50%,P:50%	cm	43
Mass Density	1183	23 °C	g/cm ³	1.1
Tensile Strength	527	50 mm/min, yield	MPa	50
		50 mm/min, break	MPa	42
Tensile Elongation	527	50 mm/min	%	105
Flexural Strength	178	2 mm/min	MPa	75
Flexural Modulus		2 mm/min	GPa	2.1
Izod Impact Strength	180/1A	23°C, Notched, 3.2mm	KJ/m ²	45
		-30°C, Notched, 3.2mm	KJ/m ²	40
Charpy Impact Strength	179	23°C, Notched, 3.2mm	KJ/m ²	45
		-30°C, Notched, 3.2mm	KJ/m ²	40
Vicat Softening Temp.	306	50°C/hr;1KG	°C	125
		50°C/hr;5KG	°C	110
Heat Distortion Temp.	75/A	1.8MPa, unannealed	°C	93
		1.8MPa, annealed	°C	-
Dielectric Constant	IEC 60250	1MHz	--	3.1
Volume Resistivity	IEC 60093	--	Ohm X m	1E+16
Surface Resistivity	IEC 60093	--	Ohm	1E+16
Coefficient of Linear Thermal Expansion	11359	-	-	8.5*10 ⁻⁵
Flammability	-	UL-94	-	1.5mm HB
Mold Shrinkage	294-4	-	%	0.4~0.6
Symbol	1043	-	-	>PC+ABS<

September 23, 2025

Notes: The value provided herein has been established on above test methods and conditions, which only as reference for selecting material, NOT guaranteed values or formal specifications. There can be variation within normal tolerances in colors.

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